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148th Annual Meeting & Exhibition

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March 10–14, 2019
San Antonio, Texas, USA

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ELECTRONIC MATERIALS

Advanced Microelectronic Packaging, Emerging Interconnection Technology, and Pb-free Solder

Continuing advances in microelectronic, optoelectronic, and nanoelectronic devices require new materials and technologies to meet the increasing electrical, thermal, mechanical, reliability, performance, and environmental demands placed on interconnects and packaging at all levels. This symposium will address current researches in Packaging Materials and Process, including lead-free solder, alternative interconnects, conductive adhesive, epoxy, substrates, 3D packaging, wafer level packaging, quality, reliability, and failure analysis.

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